

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1-11 (cancelled)

12. (previously presented) An electronic package comprising:
a device carrier composed of a metal surface and a lead frame enclosed by said metal surface;
at least a semiconductor unit including at least an electrode; and
at least an interconnection portion including a first part and a second part, wherein said second part directly contacts said metal surface and said semiconductor unit, both said first part and said second part span between and tie together said metal surface and said semiconductor unit, said first part and said second part respectively have an end on said metal surface, said end of said second part is surrounded by said end of said first part, said end of said first part is surrounded by said metal surface, said second part is wrapped by said first part, said first part has a melting point lower than that of said second part, and said first part adheres to said second part.

13. (original) The electronic package according to claim 12 wherein said interconnection portion electrically connects said metal surface and said semiconductor unit.

14. (previously presented) The electronic package according to claim 12 wherein said interconnection portion mechanically connects said metal surface and said semiconductor unit.

15. (original) The electronic package according to claim 12 wherein said first part contains more tin than lead, while said second part contains more lead than tin.

16. (previously presented) The electronic package according to claim 12 wherein one side of said lead frame faces semiconductor unit, and is fully covered by one part of said metal surface, said part of said metal surface is flat.

17. (previously presented) The electronic package according to claim 12 wherein said metal surface is exposed.

18. (previously presented) The electronic package according to claim 12 wherein said second part is sealed by said first part, said metal surface, and said semiconductor unit.

19. (previously presented) The electronic package according to claim 12 wherein said first part contains materials by which the solder wettability between said first part and said second part is controlled by said second part.

20. (previously presented) The electronic package according to claim 12 wherein said first part has an end partially contacting the electrode of said semiconductor unit and partially

contacting an area which is part of said semiconductor unit and which surrounds the electrode of said semiconductor unit.